

# Material Declaration Report

Package Type:	LQFP 48L
Pericom Package Code:	FB48(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	183.070
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	3
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	8/11/2008

## Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	117.000	OSE	Silica Fused	60676-86-0	89.800	105.0660
			Epoxy Resin	Proprietary	5.000	5.8500
			Phenolic Resin	Proprietary	4.000	4.6800
			Others	Proprietary	1.000	1.1700
			Carbon Black	1333-86-4	0.200	0.2340
LEADFRAME	53.000		Copper (Cu)	7440-50-8	94.900	50.2970
			Nickel (Ni)	7440-02-0	3.200	1.6960
			Silicon (Si)	7440-21-3	0.720	0.3816
			Magnesium (Mg)	7439-95-4	0.180	0.0954
			Silver(Ag)	7440-22-4	1.000	0.5300
SILICON DIE	3.940		Silicon (Si)	7440-21-3	99.192	3.9082
			Non-hazardous Metal	Proprietary	0.808	0.0318
DIE ATTACH EPOXY	0.340		Silver	7440-22-4	76.000	0.2584
			Acrylic Resin	Proprietary	8.000	0.0272
			Acrylate	Proprietary	5.500	0.0187
			Polybutadiene derivative	Proprietary	5.500	0.0187
			Epoxy resin	Proprietary	2.500	0.0085
			Additive	Proprietary	1.000	0.0034
			Butadiene copolymer	Proprietary	1.000	0.0034
Peroxide	Proprietary	0.500	0.0017			
GOLD WIRE	1.890		Gold(Au)	7440-57-5	99.990	1.8898
			Impurities	-	0.010	0.0002
SOLDER PLATING	6.900		Tin (Sn)	7440-31-5	99.990	6.8993
			Impurity	-	0.010	0.0007

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC  and  China RoHS Directive SJ/T11363-2006	<b>Declaration Statement:</b>	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.  
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.